

ABSTRACT OF THE DISCLOSURE

The present invention relates to a high frequency circuit module in which a two or more layer dielectric substrate is used. The dielectric substrate provided between a conductor line of a matching circuit on the input side or on the output side and a metal ground is composed of two or more layers. Since a required part can be increased in thickness without changing the thickness of the whole dielectric substrate, the transmission loss can be reduced and the miniaturization of the high frequency circuit module and the communication device using the same can be realized.